No.	o. Item		Specifications		Test Method
1	Operating Temperature Range		-55 to +125℃		_
2			No defects or abnormalities	Visual inspection	
3	Dimension	ns	Within the specified dimensions	Using calipers and micrometers	
4	Dielectric Strength		No defects or abnormalities	No failure should be observed when voltage in the table is applied between the terminations for 60±1 sec., provided the charge/discharge current is less than 50mA.	
				Type GB Type GC/GD Type GF	Test Voltage DC1075V AC1500V (r.m.s.) AC2000V (r.m.s.)
5	Pulse Voltage (Application: Type GD/GF)		No self healing breakdowns or flash-overs have taken place in the capacitor.	10 impulses of alternating polarity are subjected. (5 impulses for each polarity) The interval between impulses is 60 sec. Applied Pulse: 1.2/50µs Applied Voltage: 2.5kVo-p	
6	Insulation R (I.R.)	Resistance	More than $6{,}000M\Omega$	The insulation resistance should be measured with DC500±50V and within 60±5 sec. of charging.	
7	Capacitar	nce	Within the specified tolerance		
8	Dissipation Factor (D.F.) Q		Char.         Specification           X7R         D.F.≤0.025           SL         Q≥400+20C*² (C<30pF)	The capacitance/Q/D.F. should be measured at a frequency of 1±0.2kHz (SL char.: 1±0.2MHz) and a voltage of AC1±0.2V (r.m.s.)	
9	Capacitance Temperature Characteristics		Char.     Capacitance Change       X7R     Within ±15%       Temperature characteristic guarantee is −55 to +125°C       Char.     Temperature Coefficient       SL     +350 to −1000ppm/°C       Temperature characteristic guarantee is +20 to +85°C	Step  1 2 3 4 5  SL char.: The capacitance should b 3 and step 4.	nt at 150 <sup>±</sup> ₁8°C for 60±5 min. and then
		Appearance	No defects or abnormalities		nade 50 times at 5 sec. intervals from
		I.R.	More than 1,000M $\Omega$	ine capacitor (Cd) charge	ed at DC voltage of specified.
10	Discharge Test (Application: Type GC)	ation: Dielectric	tion:  Dielectric In accordance with item No.4		r under test $Cd: 0.001 \mu F$ 100M $\Omega$ R3: Surge resistance
11	Adhesive Strength of Termination		No removal of the terminations or other defect should occur.	in Fig. 1. Then apply 10N force in to should be done using the	e testing jig (glass epoxy board) shown he direction of the arrow. The soldering e reflow method and should be nat the soldering is uniform and free of ck.  10N, 10±1s Glass Epoxy Board Fig. 1

muRata

Continued on the following page.



 $<sup>^{*1} \ &</sup>quot;Room \ condition" \ \ Temperature: 15 \ to \ 35 \ ^{\circ}\!C, \ \ Relative \ humidity: 45 \ to \ 75 \%, \ \ Atmospheric \ pressure: 86 \ to \ 106 \ kPa$ 

<sup>\*2 &</sup>quot;C" expresses nominal capacitance value (pF).

Continued from the preceding page.

No.	lo. Item		Specifications	Test Method	
12	Vibration Resistance	Appearance Capacitance  D.F. Q	No defects or abnormalities  Within the specified tolerance  Char. Specification  X7R D.F.≤0.025  SL Q≥400+20C*² (C<30pF) Q≥1000 (C≥30pF)	Solder the capacitor to the test jig (glass epoxy board).  The capacitor should be subjected to a simple harmonic motion having a total amplitude of 1.5mm, the frequency being varied uniformly between the approximate limits of 10 and 55Hz. The frequency range, from 10 to 55Hz and return to 10Hz, should be traversed in approximately 1 min. This motion should be applied for a period of 2 hrs. in each of 3 mutually perpendicular directions (total of 6 hrs.).  Solder resist	
13	13 Deflection		No marking defects	Solder the capacitor to the testing jig (glass epoxy board) shown in Fig. 2.  Then apply a force in the direction shown in Fig. 3. The soldering should be done using the reflow method and should be conducted with care so that the soldering is uniform and free of defects such as heat shock.  Pressurizing speed: 1.0mm/s pressurize  Pressurize  Flexure=1  Capacitance meter  (in mm)  Fig. 3	
14	Solderability of Termination 75% of the terminations are to be soldered evenly and continuously.		75% of the terminations are to be soldered evenly and continuously	Immerse the capacitor in a solution of ethanol (JIS-K-8101) and rosin (JIS-K-5902) (25% rosin in weight proportion). Immerse in solder solution for 2±0.5 sec. Immersing speed: 25±2.5mm/s Temp. of solder: 245±5°C Lead Free Solder (Sn-3.0Ag-0.5Cu) 235±5°C H60A or H63A Eutectic Solder	
15		Appearance	No marking defects	solder solution at 260±5°C for 10±1 sec. Let sit at room condition*¹ for 24±2 hrs., then measure.  Within ±10%  Within ±2.5% or ±0.25pF (Whichever is larger)  solder solution at 260±5°C for 10±1 sec. Let sit at room condition*¹ for 24±2 hrs., then measure.  •Immersing speed: 25±2.5mm/s •Pretreatment for X7R char.  Perform a heat treatment at 150±18°C for 60±5 min. and then let sit for 24±2 hrs. at room condition *¹	
	Resistance to Soldering - Heat	Capacitance Change	X7R Within ±10% SI Within ±2.5% or ±0.25pF		
		Dielectric Strength In accordance with item No.4		*Preheating    Step   Temperature   Time     1	

<sup>\*1 &</sup>quot;Room condition" Temperature: 15 to 35°C, Relative humidity: 45 to 75%, Atmospheric pressure: 86 to 106kPa

Continued on the following page.



 $<sup>^{*}2\,^{&</sup>quot;}C"$  expresses nominal capacitance value (pF).

Continued from the preceding page.

No.	o. Item		Specifications	Test Method		
	Temperature Cycle	Appearance Capacitance Change	No marking defects  Char. Capacitance Change X7R Within ±15% SL Within ±2.5% or ±0.25pF	Fix the capacitor to the supporting jig (glass epoxy board) show in Fig. 4.  Perform the 5 cycles according to the 4 heat treatments listed the following table.  Let sit for 24±2 hrs. at room condition,*1 then measure.		
16		D.F. Q I.R. Dielectric Strength	$\begin{tabular}{ c c c c c }\hline Char. & Specification \\\hline X7R & D.F. \le 0.05 \\\hline SL & Q \ge 400 + 20C^{*2} & (C < 30pF) \\\hline Q \ge 1000 & (C \ge 30pF) \\\hline More than 3,000M$\Omega\\\\\hline \end{tabular}$	Step Temperature (°C) Time (min.)  1 Min. Operating Temp.±3 30±3 2 Room Temp. 2 to 3 3 Max. Operating Temp.±2 30±3 4 Room Temp. 2 to 3  • Pretreatment for X7R char.  Perform a heat treatment at 150 <sup>±</sup> -18°C for 60±5 min. and then let sit for 24±2 hrs. at room condition.*1    Solder resist   Solder resist   Cu   Glass Epoxy Board   Cu   Fig. 4		
17	Humidity (Steady State)	Capacitance Change  D.F. Q  I.R.  Dielectric Strength	No marking defects	Before this test, the test shown in the following is performedItem 11 Adhesive Strength of Termination (applied force is 5N) -Item 13 Deflection  Let the capacitor sit at 40±2°C and relative humidity of 90 to 95% for 500±2°5 hrs.  Remove and let sit for 24±2 hrs. at room condition,*¹ then measure.  • Pretreatment for X7R char.  Perform a heat treatment at 150±1°C for 60±5 min. and then let sit for 24±2 hrs. at room condition.*¹		
18	Life	Appearance Capacitance Change  D.F. Q  I.R.  Dielectric Strength	No marking defects	Before this test, the test shown in the following is performed.  -Item 11 Adhesive Strength of Termination (apply force is 5N) -Item 13 Deflection  Impulse Voltage Each individual capacitor should be subjected to a 2.5kV (Type GC/GF: 5kV) Impulse (the voltage value means zero to peak) for three times. Then the capacitors are applied to life test.  Apply voltage as in Table for 1,000 hrs. at $125^{+2}_{-0}$ °C, relative humidity 50% max.  Type Applied Voltage  GB AC312.5V (r.m.s.), except that once each hour the voltage is increased to AC1,000V (r.m.s.) for 0.1 sec.  GC GF GD  AC425V (r.m.s.), except that once each hour the voltage is increased to AC1,000V (r.m.s.) for 0.1 sec.  Let sit for 24±2 hrs. at room condition,*1 then measure.  • Pretreatment for X7R char.  Perform a heat treatment at $150^{+1}$ °C for $60\pm5$ min. and then let sit for $24\pm2$ hrs. at room condition.*1		

<sup>\*1 &</sup>quot;Room condition" Temperature: 15 to 35°C, Relative humidity: 45 to 75%, Atmospheric pressure: 86 to 106kPa

Continued on the following page.



<sup>\*2 &</sup>quot;C" expresses nominal capacitance value (pF).

Continued from the preceding page.

No.	No. Item		Specifications	Test Method	
19		Appearance	No marking defects		
	Humidity Loading	Capacitance Change	Char. Capacitance Change  X7R Within ±15%  SL Within ±5.0% or ±0.5pF (Whichever is larger)	Before this test, the test shown in the following is performedItem 11 Adhesive Strength of Termination (apply force is 5N) -Item 13 Deflection	
		D.F. Q	Char.         Specification           X7R         D.F.≤0.05           SL         Q≥275+5/2C*² (C<30pF)	Apply the rated voltage at 40±2°C and relative humidity of 90 to 95% for 500±2°d hrs. Remove and let sit for 24±2 hrs. at room condition,*1 then measure.  • Pretreatment for X7R char.  Perform a heat treatment at 150±18°C for 60±5 min. and then let sit for 24±2 hrs. at room condition.*1	
		I.R.	More than $3{,}000M\Omega$		
		Dielectric Strength	In accordance with item No.4		
20	Active		The cheesecloth should not be on fire.	The capacitor should be individually wrapped in at least one but not more than two complete layers of cheesecloth. The capacitor should be subjected to 20 discharges. The interval between successive discharges should be 5 sec. The UAc should be maintained for 2 min. after the last discharge.	
21	Passive Flammability		The burning time should not exceed 30 sec. The tissue paper should not ignite.	The capacitor under test should be held in the flame in the position which best promotes burning. Each specimen should be exposed to the flame only once. Time of exposure to flame: 30 sec.  Length of flame: 12±1mm  Gas burner : Length 35mm min. Inside Dia. 0.5±0.1mm Outside Dia. 0.9mm max.  Gas : Butane gas Purity 95% min.  Test Specimen  Tissue About 10mm Thick Board	

<sup>\*1 &</sup>quot;Room condition" Temperature: 15 to 35°C, Relative humidity: 45 to 75%, Atmospheric pressure: 86 to 106kPa

<sup>\*2 &</sup>quot;C" expresses nominal capacitance value (pF).